

**Amendments to th Claims:**

A listing of the entire set of pending claims (including amendments to the claims, if any) is submitted herewith per 37 CFR 1.121. This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1. (Original) A method of manufacturing a display device, in which a substrate is provided with groups of at least one pixel and a conductor pattern and in which a semiconductor device for supplying drive voltages to the pixel is fixed to the substrate, the method comprising the steps of
  - providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,
  - mutually separating the semiconductor devices in a surface region of the semiconductor substrate,
  - coupling the electric connection contacts to the conductor pattern, and
  - subsequently separating the semiconductor devices from the semiconductor substrate.
2. (Original) A method as claimed in claim 1, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.
3. (Original) A method of manufacturing a display device, in which a substrate is provided with groups of at least one pixel and in which a semiconductor device for supplying drive voltages to the pixel is fixed to the substrate, the method comprising the steps of
  - providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,

mutually separating the semiconductor devices in a surface region of the semiconductor substrate,

subsequently separating the semiconductor devices from the semiconductor substrate, and

subsequently providing the substrate with a conductor pattern at least at the location of the semiconductor devices and coupling the electric connection contacts to the conductor pattern.

4. (Original) A method as claimed in claim 3, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.

5. (Previously presented) A method as claimed in claim 1, wherein the semiconductor devices have the same pitch as the groups of pixels in at least one dimension.

6. (Previously presented) A method as claimed in claim 1, wherein a semiconductor device is associated with a plurality of pixels.

7. (Original) A method as claimed in claim 6, wherein the semiconductor device comprises drive electronics for the pixels.

8. (Previously presented) A method as claimed in claim 1, wherein the semiconductor devices are separated by means of an etching treatment in a surface region of the semiconductor substrate.

9. (Previously presented) A method as claimed in claim 1, wherein the semiconductor devices are provided in a semiconductor layer on an insulating layer (19) and are separated by means of an etching treatment.

10. (Previously presented) A method as claimed in claim 1, wherein the substrate is flexible.

11. (Original) A method of manufacturing an electronic device, in which at least a substrate is provided with functional groups comprising at least a switching element, and in which a semiconductor device for supplying drive voltages to the switching element is fixed to the substrate, the method comprising the steps of

- providing the substrate with a conductor pattern,
- providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,
- mutually separating the semiconductor devices in a surface region of the semiconductor substrate,
- coupling the electric connection contacts to the conductor pattern, and
- subsequently separating the semiconductor devices from the semiconductor substrate.

12. (Original) A method as claimed in claim 11, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.

13. (Original) A method of manufacturing an electronic device, in which at least a substrate is provided with functional groups comprising at least a switching element, and in which a semiconductor device for supplying drive voltages to the switching element is fixed to the substrate, the method comprising the steps of

- providing a semiconductor substrate with a plurality of semiconductor devices having electric connection contacts on their surfaces,
- mutually separating the semiconductor devices in a surface region of the semiconductor substrate,
- subsequently separating the semiconductor devices from the semiconductor substrate, and providing the substrate with a conductor pattern and coupling the electric connection contacts to the conductor pattern.

14. (Original) A method as claimed in claim 13, wherein at least a part of the electric connection contacts is connected to the conductor pattern in an electrically conducting manner.
15. (Previously presented) A method as claimed in claim 11, wherein the semiconductor devices have the same pitch as the functional groups in at least one dimension.
16. (New) The method of claim 3, wherein the semiconductor devices have the same pitch as the groups of pixels in at least one dimension.
17. (New) The method of claim 3, wherein a semiconductor device is associated with a plurality of pixels.
18. (New) The method of claim 3, wherein the semiconductor devices are separated by means of an etching treatment in a surface region of the semiconductor substrate.
19. (New) The method of claim 3, wherein the semiconductor devices are provided in a semiconductor layer on an insulating layer (19) and are separated by means of an etching treatment.
20. (New) The method of claim 3, wherein the substrate is flexible.
21. (New) The method of claim 13, wherein the semiconductor devices have the same pitch as the functional groups in at least one dimension.